

METHOD FOR ELECTRICAL TESTING OF SEMICONDUCTOR PACKAGE THAT
DETECTS SOCKET DEFECTS IN REAL TIME

ABSTRACT OF THE DISCLOSURE

5 An electrical testing method for a semiconductor package for detecting defects of
sockets mounted on a device under test (DUT) board is provided. A tester performs electrical
test, accumulates electrical test results, and compares the accumulated results to reference
values. The result of the comparison decides whether a plurality of sockets mounted on the
DUT board can be used or not. The decision results are transmitted to a handler so that the
10 socket having the defects is not used on the DUT board.